

ATTORNEY DOCKET NO. 02-C-088 (STMI01-00088)
U.S. SERIAL NO. 10/611,578
PATENT

AMENDMENTS TO THE SPECIFICATION:

Please replace paragraph [0005] (at page 2, lines 9-19) of the specification with the following:

[0005] FIGURE 1 illustrates a cross sectional view 100 of a prior art wire bond pad 120 and a prior art ball bond 150 of wire 140 bonded to the wire bond pad 120. Wire bond pad 120 is made of a metal conductor such as aluminum or copper. During the process of fabrication, wire bond pad 120 is placed on substrate material 110 (e.g., silicon). The edges of wire bond pad 120 are then covered with passivation material 130. A central portion of the external surface of wire bond pad 120 is open to receive ball 150 on the end of wire 140. Ball 150 is placed on wire bond pad 120 and bonded to wire bond pad 120 using a prior art wirebonding technique.